

S1C17 Family Technical Manual Errata

ITEM Pad/Bump Configuration			
Object manual	Document code	Object item	Page
S1C17653 Technical Manual	412355800	24.2.1 Pad/Bump Configuration	24-2
<p>(Error)</p> <p>Chip size X = 2.637 mm, Y = 2.543 mm</p> <p>Pad opening No. 1 to 17, 37 to 47: X = 76 μm, Y = 85 μm</p> <p>No. 18 to 36, 48 to 67: X = 85 μm, Y = 76 μm</p> <p>Bump size No. 1 to 17, 37 to 47: X = 70 μm, Y = 79 μm</p> <p>No. 18 to 36, 48 to 67: X = 79 μm, Y = 70 μm</p> <p>Chip thickness 400 μm</p>			
<p>(Correct)</p> <p>Chip size X = 2.637 mm, Y = 2.543 mm</p> <p>Pad opening No. 1 to 17, 37 to 47: X = 76 μm, Y = 85 μm</p> <p>No. 18 to 36, 48 to 67: X = 85 μm, Y = 76 μm</p> <p>Bump size No. 1 to 17, 37 to 47: X = 70 μm, Y = 79 μm</p> <p>No. 18 to 36, 48 to 67: X = 79 μm, Y = 70 μm</p> <p>Chip thickness 400 μm</p> <p>Alignment mark: Upper left (X:-1206.1um, Y:1159.1um) Lower right(X:1206.1um, Y:-1095.1um)</p>			